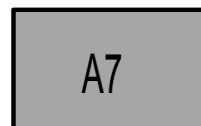
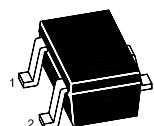


Features

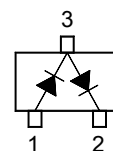
Fast Switching Speed
Ultra-Small Surface Mount Package
For General Purpose Switching Applications
High Conductance



SOT-323



Equivalent Circuit



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

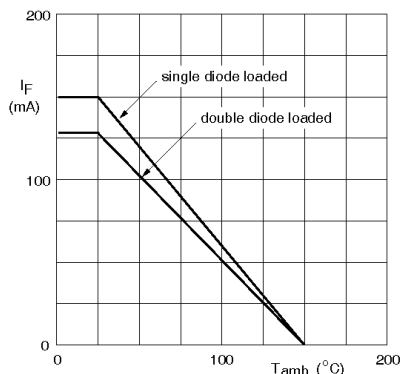
MAXIMUM RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Repetitive Peak Reverse Voltage	V_{RRM}	85	V
Reverse Voltage	V_R	75	V
Continuous Forward Current	I_F	150	mA
Single Diode Load Double Diode Load		130	
Repetitive Peak Forward Current	I_{FRM}	500	mA
Non-Repetitive Peak Forward Surge Current	I_{FSM}	4	A
at $t = 1\ \mu\text{s}$		1	
at $t = 1\ \text{ms}$ at $t = 1\ \text{s}$		0.5	
Total Power Dissipation	P_{tot}	200	mW
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	625	$^\circ\text{C/W}$
Junction Temperature	T_j	150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	- 55 to + 150	$^\circ\text{C}$

Electrical Characteristics ($T_a=25^{\circ}\text{C}$ unless otherwise noted)

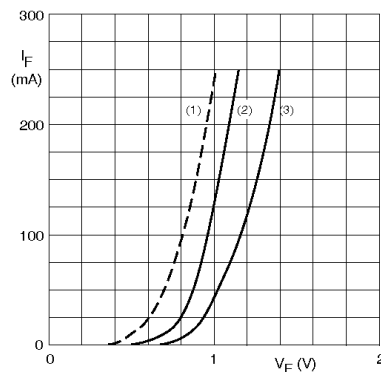
Parameter	Symbol	Max.	Unit
Forward Voltage at $I_F = 1\text{ mA}$ at $I_F = 10\text{ mA}$ at $I_F = 50\text{ mA}$ at $I_F = 150\text{ mA}$	V_F	0.715 0.855 1 1.25	V
Reverse Current at $V_R = 25\text{ V}$ at $V_R = 75\text{ V}$ at $V_R = 25\text{ V}$, $T_j = 150^{\circ}\text{C}$ at $V_R = 75\text{ V}$, $T_j = 150^{\circ}\text{C}$	I_R	30 1 30 50	nA μA μA μA
Diode Capacitance at $V_R = 0$, $f = 1\text{ MHz}$	C_d	1.5	pF
Reverse Recovery Time at $I_F = I_R = 10\text{ mA}$, $I_{rr} = 0.1 \times I_R$, $R_L = 100\ \Omega$	t_{rr}	4	ns

RATING AND CHARACTERISTIC CURVES



Device mounted on an FR4 printed-circuit board.

Maximum permissible continuous forward current as a function of ambient temperature.

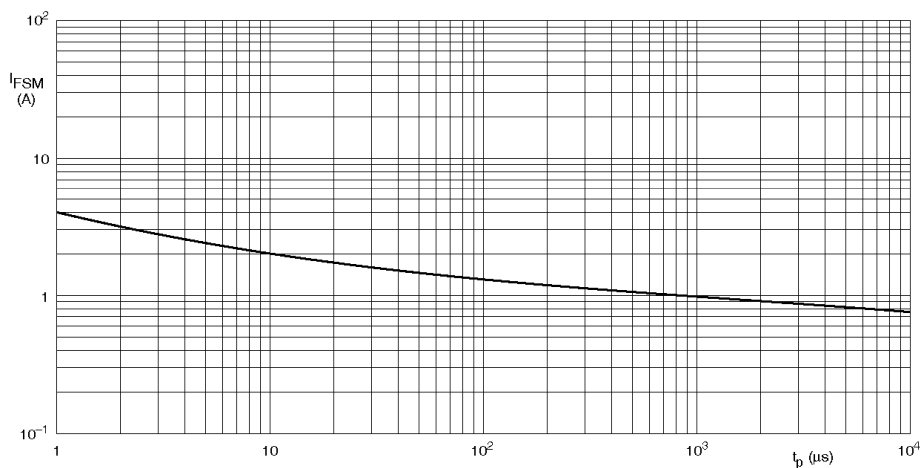


(1) $T_j = 150$ °C; typical values.

(2) $T_j = 25$ °C; typical values.

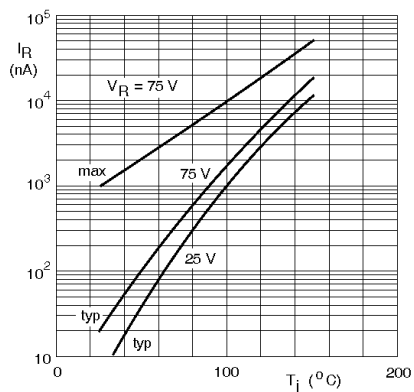
(3) $T_j = 25$ °C; maximum values.

Forward current as a function of forward voltage.

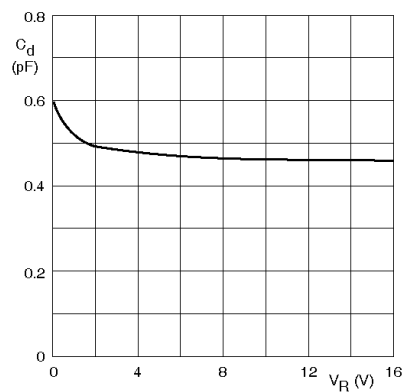


Based on square wave currents.
 $T_j = 25$ °C prior to surge.

Maximum permissible non-repetitive peak forward current as a function of pulse duration.



Reverse current as a function of junction temperature.

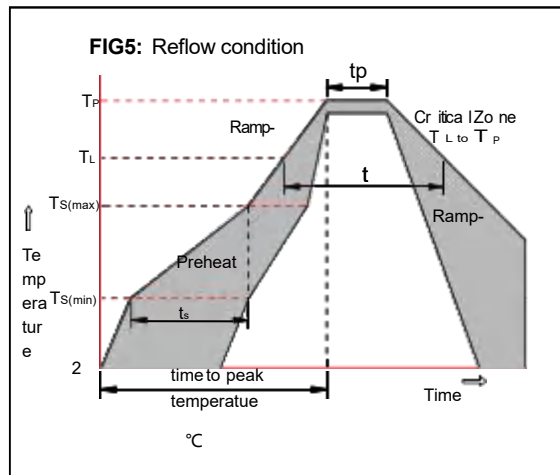


$f = 1$ MHz; $T_j = 25$ °C.

Diode capacitance as a function of reverse voltage; typical values.

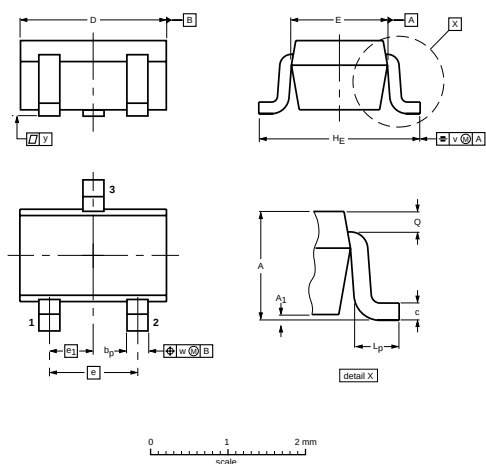
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150 °C
	-Temperature Max($T_{s(max)}$)	+200 °C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3 °C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217 °C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260 °C



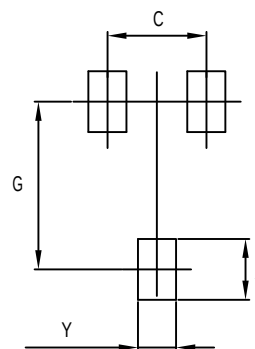
Package Dimensions & Suggested Pad Layout

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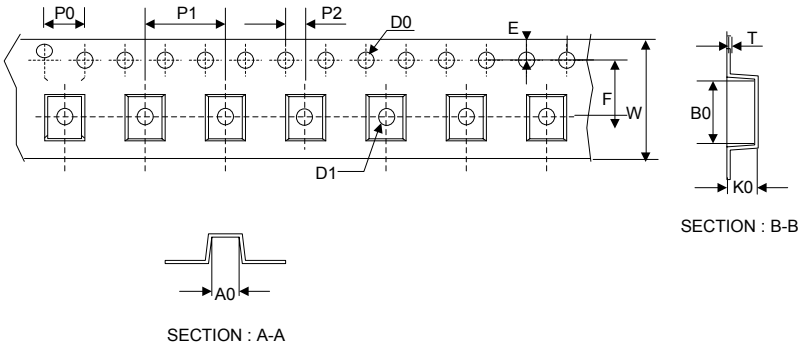
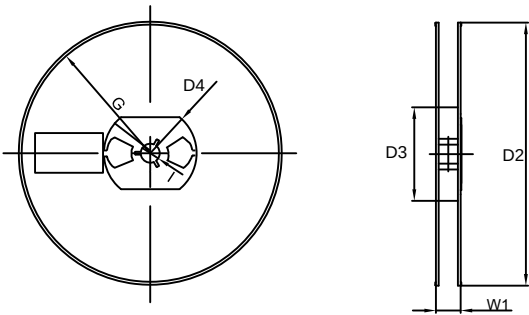
DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	b _p	c	D	E	e	e ₁	H _E	L _p	Q	v	w
mm	1.1 0.8	0.1	0.4 0.3	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2



Dimensions	Value (in mm)
C	1.30
G	2.00
X	0.90
Y	0.65

Tape & reel specification

Tape		Symbol	Dimension (mm)
		P0	4.00±0.20
		P1	4.00±0.20
		P2	2.00±0.20
		D0	1.55±0.20
		D1	1.00±0.20
		E	1.55±0.25
		F	3.60±0.20
		W	8.00±0.20
		A0	2.50±0.20
		B0	2.60±0.20
		K0	1.40±0.20
		T	0.20±0.20
		D2	177.0±5.0
		D3	55Min.
		D4	R24.6±2.0
7" Reel		G	R82.0±2.0
		I	13.0±2.0
		W1	10.20±3.0
		Quantity: 3000PCS	